The products are 1MBd high-speed opto-couplers. The device is a small-outline coupler suitable for surface-mount assembly. It consists of a high-output-power infrared LED optically coupled to a high-speed photodiode-transistor chip. It is housed in a plastic WSOP8 and guarantees a creepage distance of ≥5 mm, a clearance of ≥5 mm and an insulation thickness of ≥0.4 mm. Therefore, it meets the reinforced insulation class requirements of international safety standards. The products are widely used in programmable controllers, industrial inverters and switching power supplies.

High isolation 7500 VRMS
CTI ≥ 600
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

LED	Output
ON	L
OFF	H

(Temperature=25°C)

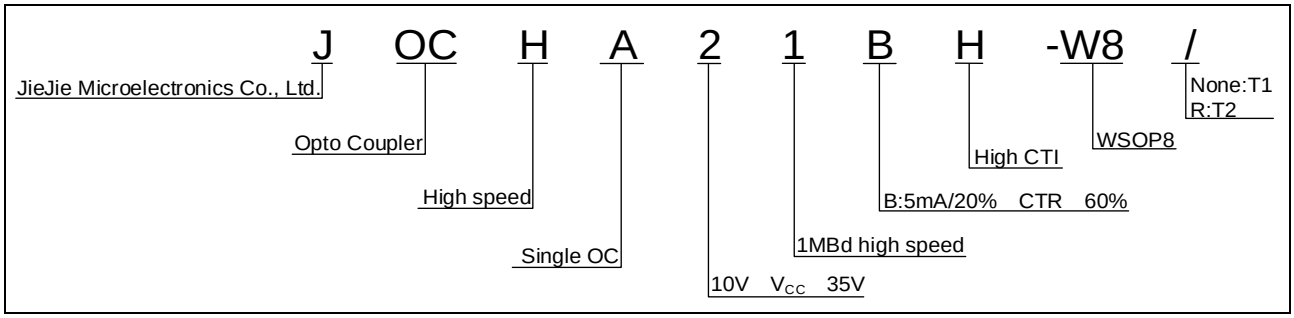
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V

	Output Current	I_O	8	mA
	Output Power Dissipation	P_O	100	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	7500	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

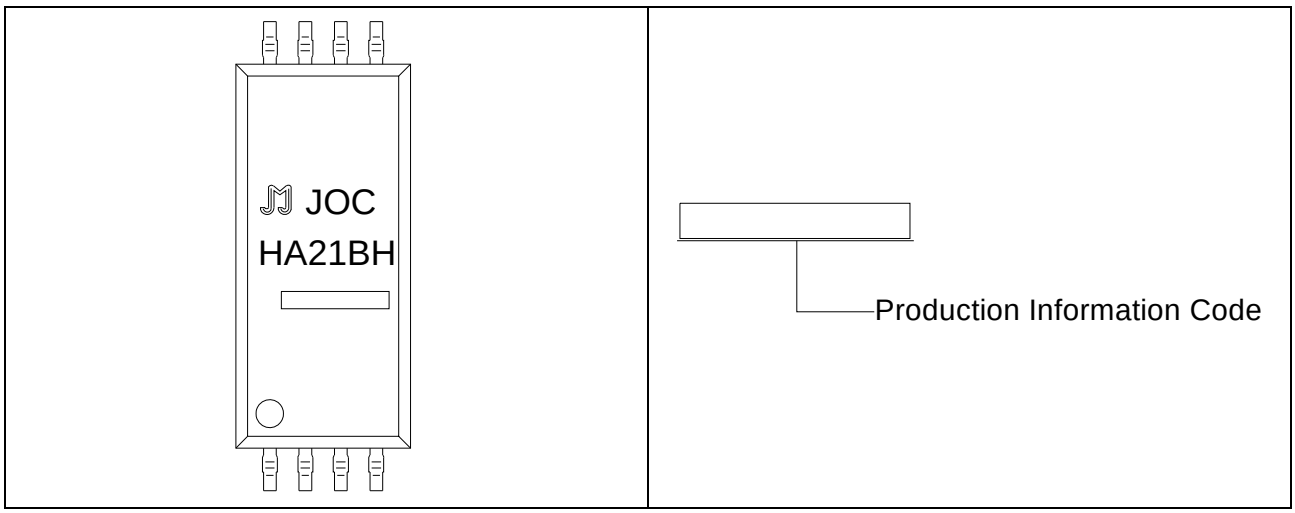
100μs pulse, 100Hz frequency

AC for 1minute, R.H.=40~60%

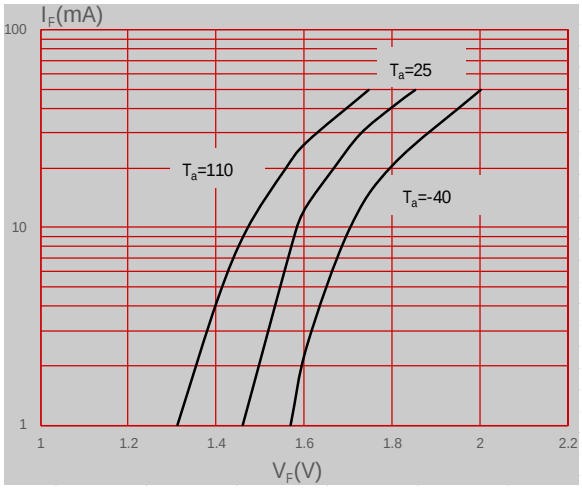
	Common Mode Transient Immunity at Logic High	CM_H	I_F=0mA, V_{CM}=400Vpp, R_L=4.1kΩ	15	20	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	I_F=16mA, V_{CM}=400Vpp, R_L=4.1kΩ	-15	-20	-	kV/μs



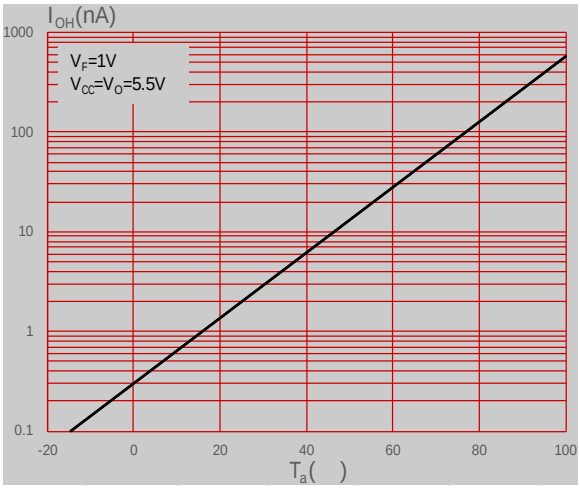
WSOP8	1200 Units/Reel	1 Reel/Inner box	5 Inner box/Outer box =6k Units



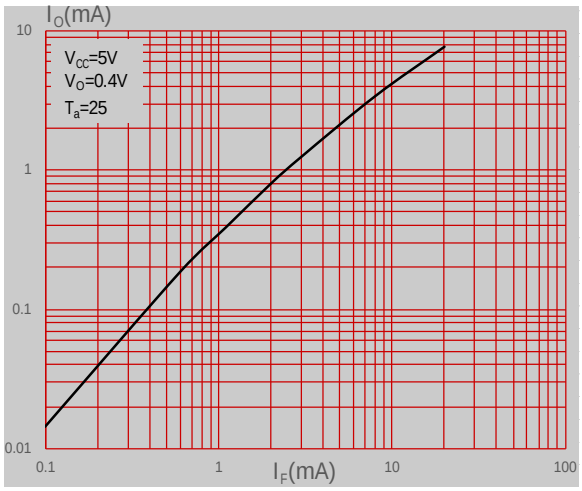
Forward Current vs. Forward Voltage



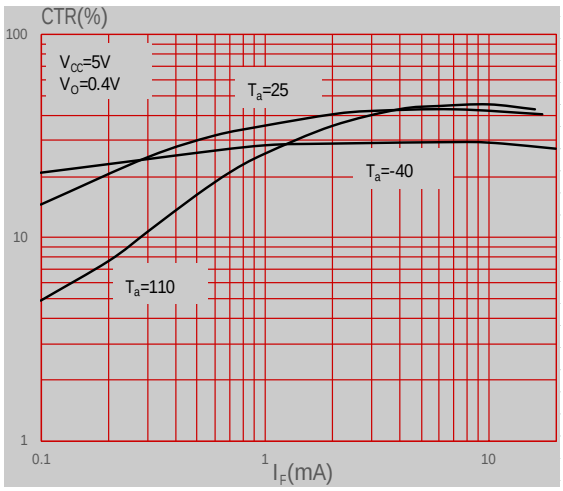
High Level Output Current vs. Ambient Temperature



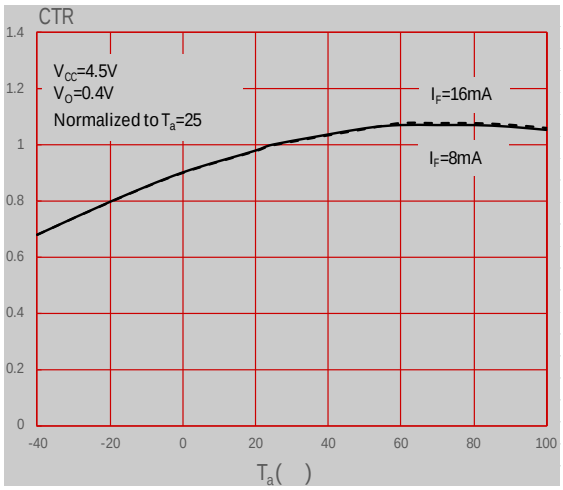
Output Current vs. Forward Current



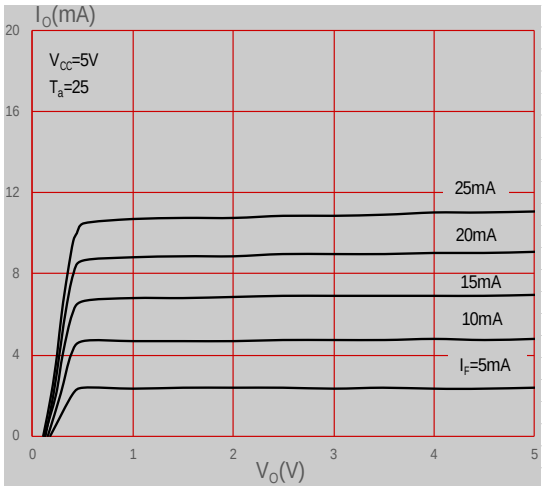
Current Transfer Ratio vs. Forward Current



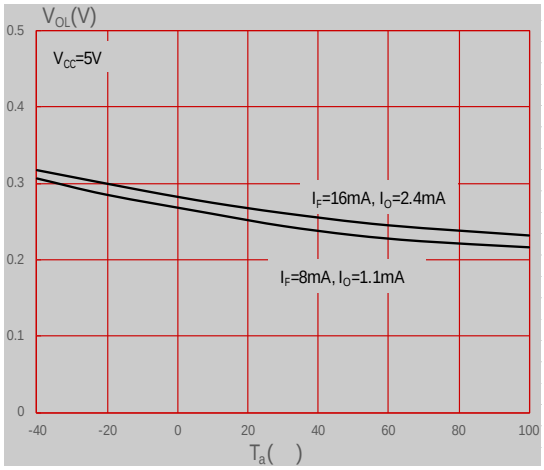
Normalized Current Transfer Ratio vs. Ambient Temperature



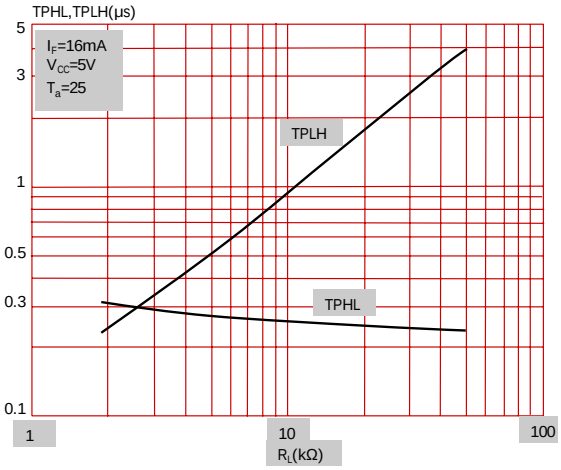
Output Current vs. Output Voltage



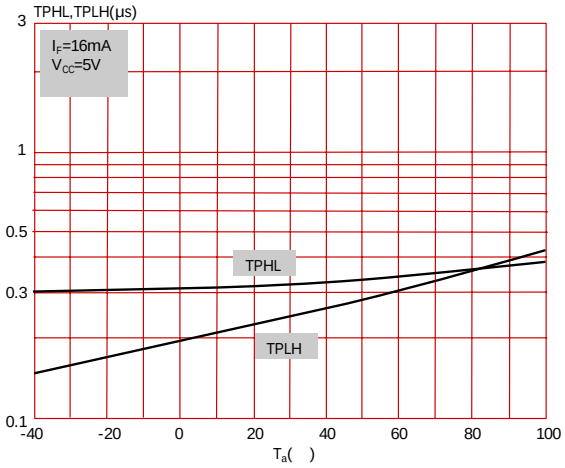
Low Level Output Voltage vs. Ambient Temperature

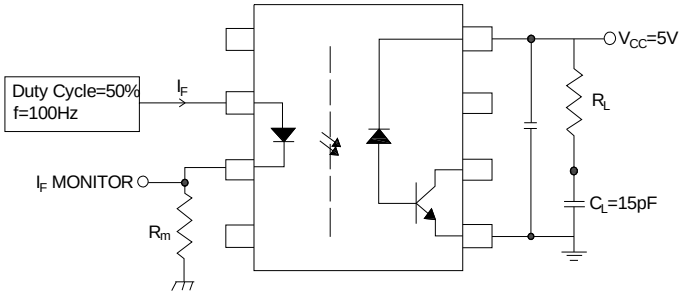


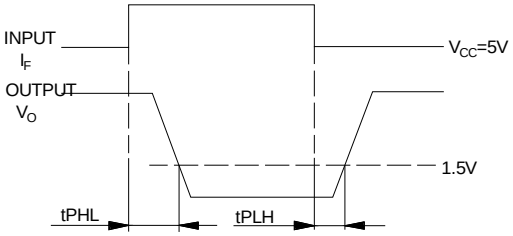
Propagation Delay vs. Load Resistance

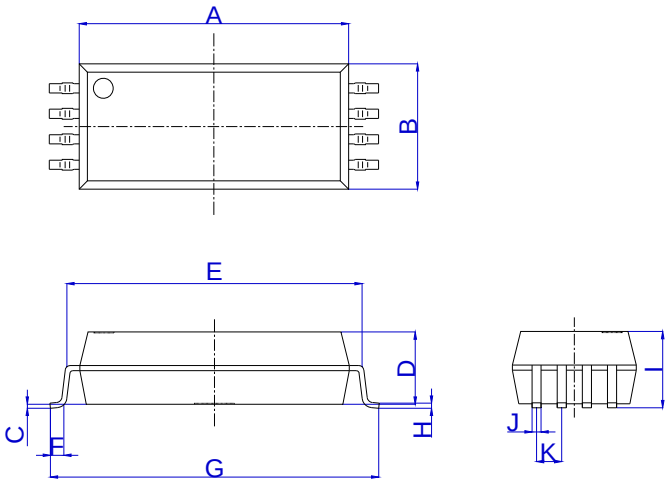


Propagation Delay vs. Ambient Temperature

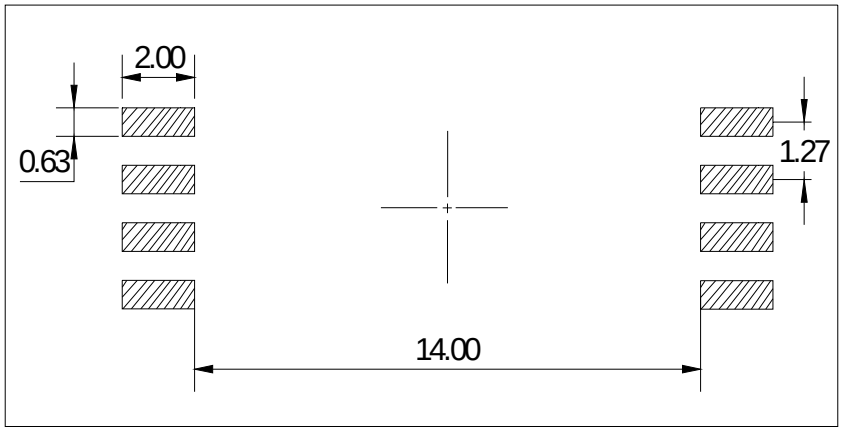


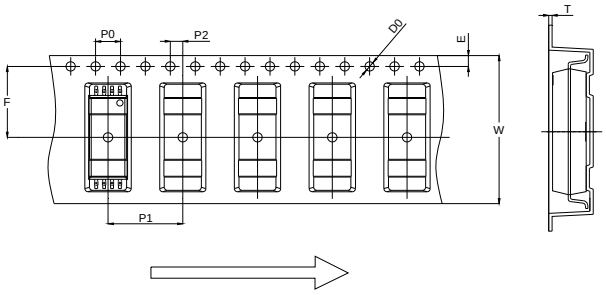

Duty Cycle=50%
f=100Hz
I_F
I_F MONITOR
R_m
V_{CC}=5V
R_L
C_L=15pF


INPUT
I_F
OUTPUT
V_O
V_{CC}=5V
1.5V
tPHL
tPLH

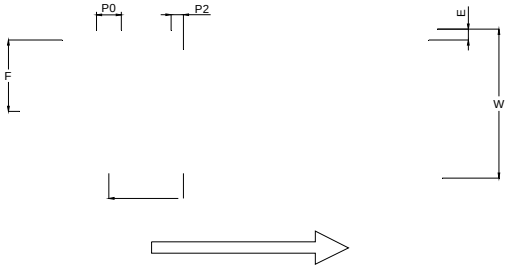


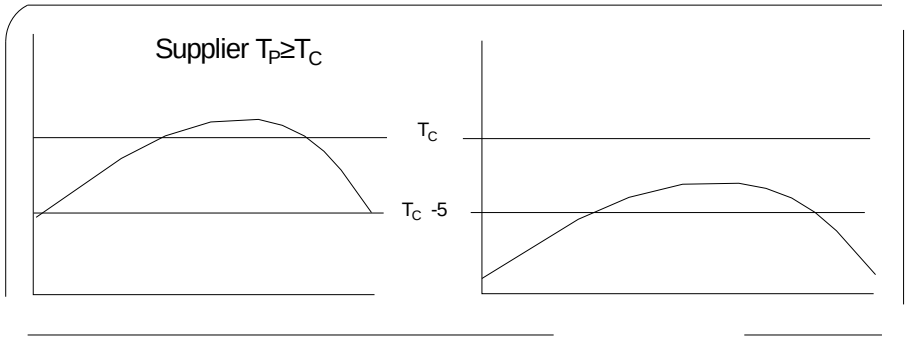
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	13.50		13.70	0.531		0.539
B	6.15		6.35	0.242		0.250
C	0.10		0.30	0.004		0.012
D	3.50		3.70	0.138		0.146
E	14.71		15.31	0.579		0.603
F	0.52		1.02	0.020		0.040
G	16.36		16.86	0.644		0.664
H	0.10		0.40	0.004		0.016
I	3.65		3.95	0.144		0.156
J	0.307		0.607	0.012		0.024
K	1.02		1.52	0.040		0.060

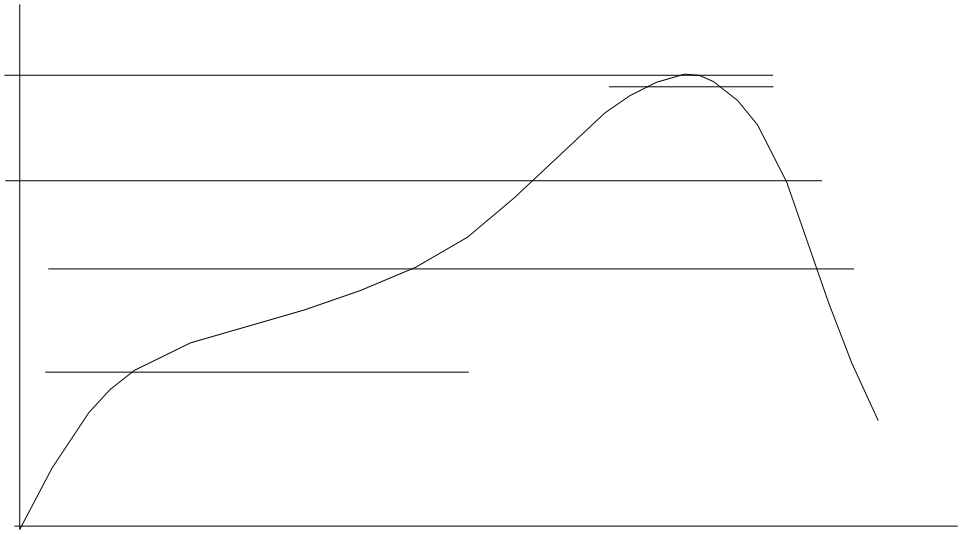




Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	11.40	11.50	11.60	0.449	0.453	0.457
T	0.35	0.40	0.45	0.014	0.016	0.018
W	23.70	24.00	24.30	0.933	0.945	0.957




Supplier $T_P \geq T_C$
T_C
T_C -5



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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